TOSHIBA Power MOS FET Module Silicon P Channel MOS Type (L²-π-MOSV 4 in 1)

# **MP4211**

High Power, High Speed Switching Applications
For Printer Head Pin Driver and Pulse Motor Driver
For Solenoid Driver

- 4 V gate drive available
- Small package by full molding (SIP 10 pin)
- High drain power dissipation (4 devices operation) :  $P_T = 4 \text{ W (Ta} = 25^{\circ}\text{C)}$
- Low drain-source ON resistance: RDS (ON) =  $0.16 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 4.0 \text{ S (typ.)}$
- Low leakage current:  $I_{GSS} = \pm 10 \mu A \text{ (max) (V}_{GS} = \pm 16 \text{ V)}$

 $I_{DSS} = -100 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = -60 \,\text{V})$ 

• Enhancement-mode:  $V_{th} = -0.8 \text{ to } -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_D = -1 \text{ mA)}$ 

## **Maximum Ratings (Ta = 25°C)**

| Characteristic   | Symbol  | Rating           | Unit       |    |  |
|--|---|------------------|------------|----|--|
| Drain-source voltage                                     |   | $V_{DSS}$        | -60        | V  |  |
| Drain-gate voltage (R <sub>GS</sub>                      | Drain-gate voltage ( $R_{GS}$ = 20 k $\Omega$ ) |                  | -60        | V  |  |
| Gate-source voltage                                      |   | V <sub>GSS</sub> | ±20        | V  |  |
| Drain current  | DC  | I <sub>D</sub>   | -5         | Α  |  |
| Diain Cuitent  | Pulse   | $I_{DP}$         | -20        | ^  |  |
| Drain power dissipation (1 device operation, Ta = 25°C)  |   | P <sub>D</sub>   | 2.0        | W  |  |
| Drain power dissipation (4 devices operation, Ta = 25°C) |   | P <sub>DT</sub>  | 4.0        | W  |  |
| Single pulse avalanche e                                 | energy<br>(Note 1)                              | E <sub>AS</sub>  | 273        | mJ |  |
| Avalanche current  |   | I <sub>AR</sub>  | -5         | Α  |  |
| Repetitive avalanche energy (Note 2)                     | 1 device operation                              | E <sub>AR</sub>  | 0.2        | mJ |  |
|  | 4 devices operation                             | E <sub>ART</sub> | 0.4        |    |  |
| Channel temperature                                      |   | T <sub>ch</sub>  | 150        | °C |  |
| Storage temperature range                                |   | T <sub>stg</sub> | −55 to 150 | °C |  |

Note 1: Avalanche energy (single pulse) applied condition

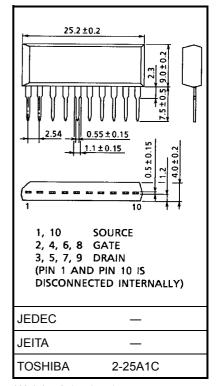
 $V_{DD}$  = -25 V, starting  $T_{ch}$  = 25°C, L = 14.84 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = -5 A

Note 2: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

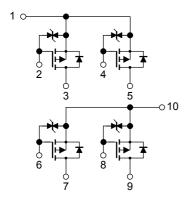
### **Industrial Applications**

Unit: mm



Weight: 2.1 g (typ.)

# **Array Configuration**



## **Thermal Characteristics**

| Characteristics  | Symbol | Max  | Unit |  |
|--|--------|------|------|--|
| Thermal resistance of channel to ambient ΣR <sub>th (ch-a)</sub> |        | 31.2 | °C/W |  |
| (4 devices operation, Ta = 25°C)                                 | . (* / |      |      |  |
| Maximum lead temperature for soldering purposes                  | TL     | 260  | ů    |  |
| (3.2 mm from case for t = 10 s)                                  |        |      |      |  |

# Electrical Characteristics (Ta = 25°C)

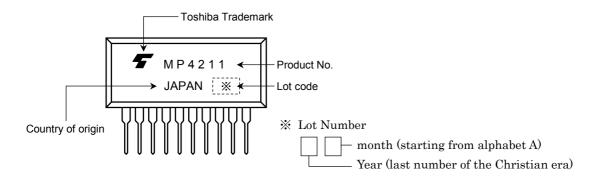
| Chara   | cteristics    | Symbol                | Test Condition  | Min  | Тур. | Max  | Unit |
|---|---------------|-----------------------|---|------|------|------|------|
| Gate leakage curr                               | ent           | I <sub>GSS</sub>      | V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V                                      | _    | _    | ±10  | μΑ   |
| Drain cut-off curre                             | ent           | I <sub>DSS</sub>      | V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V                                      | _    | _    | -100 | μΑ   |
| Drain-source brea                               | kdown voltage | V <sub>(BR) DSS</sub> | $I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$  | -60  | _    | _    | V    |
| Gate threshold vo                               | Itage         | V <sub>th</sub>       | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 mA                                     | -0.8 | _    | -2.0 | V    |
| Drain-source ON resistance                      |               | Б                     | V <sub>GS</sub> = -4 V, I <sub>D</sub> = -2.5 A                                     | _    | 0.24 | 0.28 | - Ω  |
|   |               | R <sub>DS</sub> (ON)  | $V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$                                      | _    | 0.16 | 0.19 |      |
| Forward transfer a                              | admittance    | Y <sub>fs</sub>       | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -2.5 A                                    | 2.0  | 4.0  | _    | S    |
| Input capacitance                               |               | C <sub>iss</sub>      |   | _    | 630  | _    | pF   |
| Reverse transfer capacitance                    |               | C <sub>rss</sub>      | V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                           | _    | 95   | _    | pF   |
| Output capacitance                              |               | C <sub>oss</sub>      |   | _    | 290  | _    | pF   |
| Switching time                                  | Rise time     | t <sub>r</sub>        | V <sub>GS</sub> -10 V   I <sub>D</sub> = -2.5 A   C   C   C   C   C   C   C   C   C | _    | 25   | _    | ns   |
|   | Turn-on time  | t <sub>on</sub>       |   | _    | 45   | _    |      |
|   | Fall time     | t <sub>f</sub>        |   |      | 55   | _    |      |
|   | Turn-off time | t <sub>off</sub>      | $V_{IN}$ : $t_r$ , $t_f < 5$ ns, duty $\le 1\%$ , $t_W = 10 \ \mu s$                | ı    | 200  | _    |      |
| Total gate charge (gate-source plus gate-drain) |               | Qg                    | V <sub>DD</sub> ≈ -48 V, V <sub>GS</sub> = -10 V, I <sub>D</sub> = -5 A             | _    | 22   | _    | nC   |
| Gate-source charge                              |               | Q <sub>gs</sub>       | VDD ~ -40 V, VGS10 V, ID = -5 A   | _    | 16   | _    | nC   |
| Gate-drain ("miller") charge                    |               | Q <sub>gd</sub>       |   | _    | 6    |      | nC   |

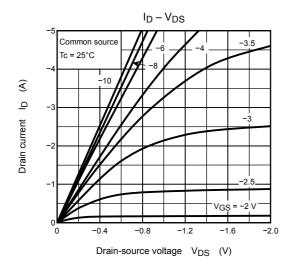
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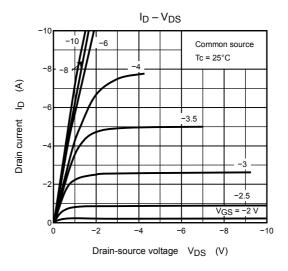
# Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

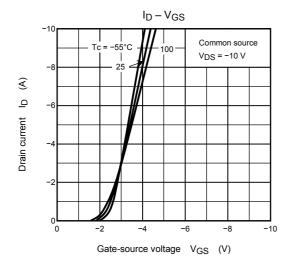
| Characteristics                  | Symbol           | Test Condition                                | Min | Тур. | Max | Unit |
|----------------------------------|------------------|---|-----|------|-----|------|
| Continuous drain reverse current | I <sub>DR</sub>  | _   | _   | _    | -5  | Α    |
| Pulse drain reverse current      | I <sub>DRP</sub> | _   | 1   | 1    | -20 | Α    |
| Diode forward voltage            | $V_{DSF}$        | $I_{DR} = -5 \text{ A}, V_{GS} = 0 \text{ V}$ | _   | _    | 1.7 | V    |
| Reverse recovery time            | t <sub>rr</sub>  | I <sub>DR</sub> = -5 A, V <sub>GS</sub> = 0 V | _   | 80   | _   | ns   |
| Reverse recovery charge          | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 50 A/µs                | _   | 0.1  | _   | μC   |

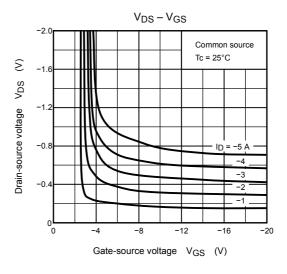
# Marking

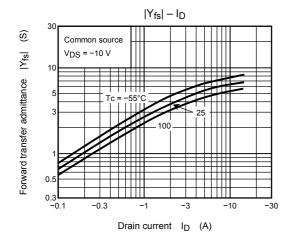


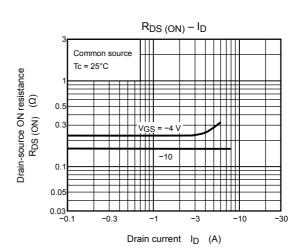


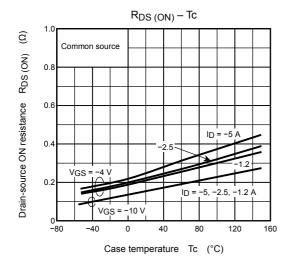


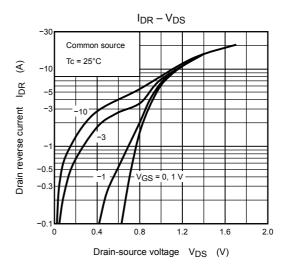


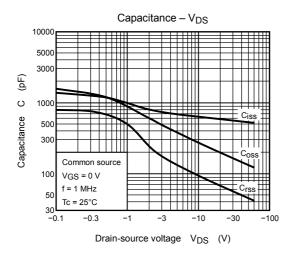


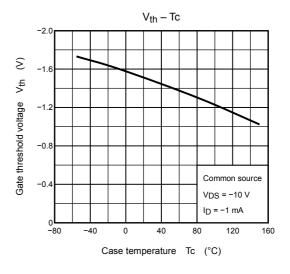


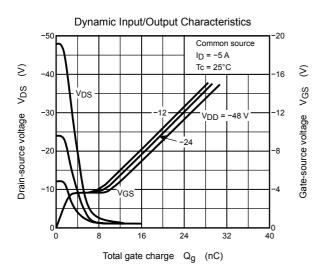


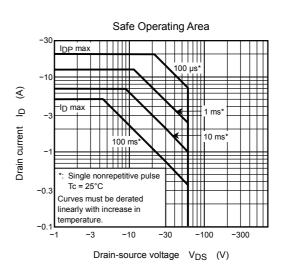


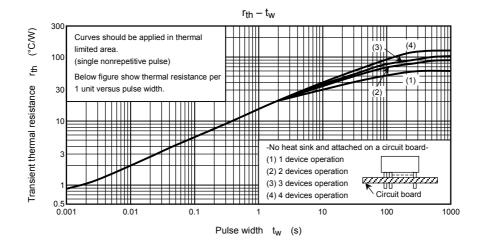


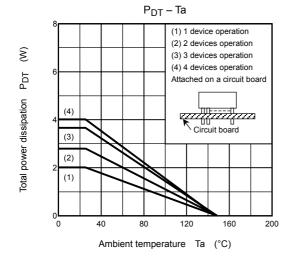


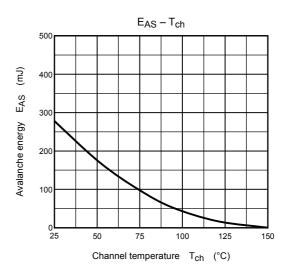


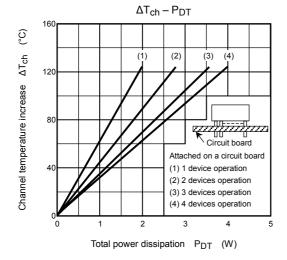


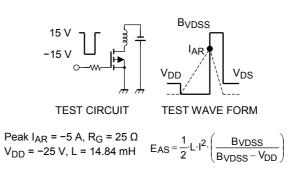












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